

# MBRA130LT3

## Surface Mount Schottky Power Rectifier SMA Power Surface Mount Package

This device employs the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

### Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Low Forward Voltage Drop
- Pb-Free Package is Available

### Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Cathode Lead Indicated by Either Notch in Plastic Body or Polarity Band
- Available in 12 mm Tape, 5000 Units per 13 inch Reel, Add "T3" Suffix to Part Number
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V)  
Human Body Model, 3B (>8000 V)

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	30	V
Average Rectified Forward Current (At Rated $V_R$ , $T_C = 105^\circ\text{C}$ )	$I_O$	1.0	A
Peak Repetitive Forward Current (At Rated $V_R$ , Square Wave, 100 kHz, $T_C = 105^\circ\text{C}$ )	$I_{FRM}$	2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	25	A
Storage Temperature	$T_{stg}$	-55 to +150	°C
Operating Junction Temperature	$T_J$	-55 to +125	°C
Voltage Rate of Change, (Rated $V_R$ , $T_J = 25^\circ\text{C}$ )	$dv/dt$	10,000	V/ $\mu\text{s}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



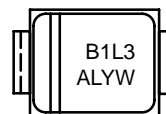
ON Semiconductor®

## SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES, 30 VOLTS



SMA  
CASE 403D  
PLASTIC

### MARKING DIAGRAM



B1L3 = Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week

### ORDERING INFORMATION

Device	Package	Shipping†
MBRA130LT3	SMA	5000/Tape & Reel
MBRA130LT3G	SMA (Pb-Free)	5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# MBRA130LT3

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance — Junction-to-Lead (Note 1)	$R_{\theta JL}$	35	$^{\circ}\text{C}/\text{W}$
Thermal Resistance — Junction-to-Ambient (Note 1)	$R_{\theta JA}$	86	$^{\circ}\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 2) see Figure 2	$V_F$ ( $I_F = 1.0 \text{ A}$ ) ( $I_F = 2.0 \text{ A}$ )	$T_J = 25^{\circ}\text{C}$	$T_J = 100^{\circ}\text{C}$	Volts
		0.41 0.47	0.35 0.43	
Maximum Instantaneous Reverse Current see Figure 4	$I_R$ ( $V_R = 30 \text{ V}$ ) ( $V_R = 15 \text{ V}$ )	$T_J = 25^{\circ}\text{C}$	$T_J = 100^{\circ}\text{C}$	mA
		1.0 0.4	25 12	

1. Mounted on 2" Square PC Board with 1" Square Total Pad Size, PC Board FR4.
2. Pulse Test: Pulse Width  $\leq 250 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

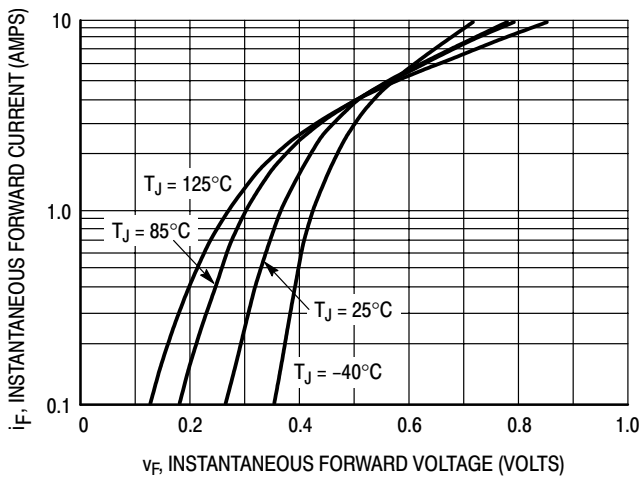


Figure 1. Typical Forward Voltage

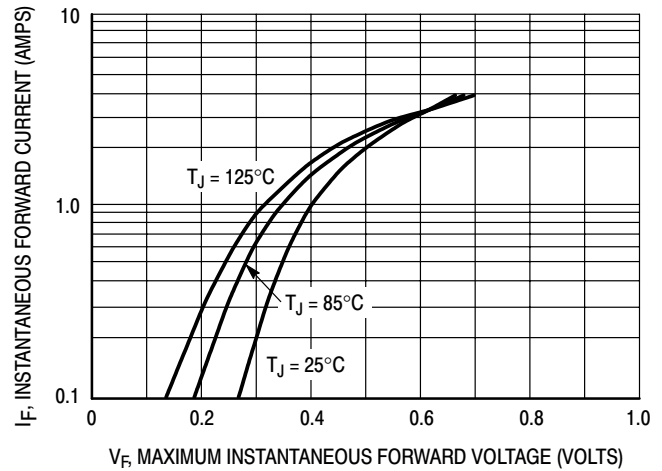


Figure 2. Maximum Forward Voltage

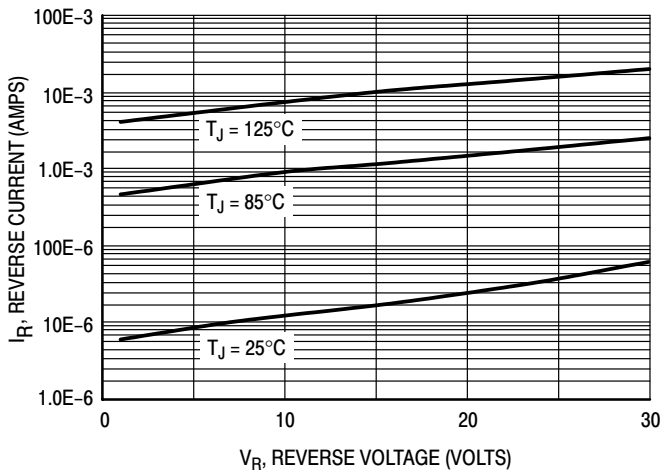


Figure 3. Typical Reverse Current

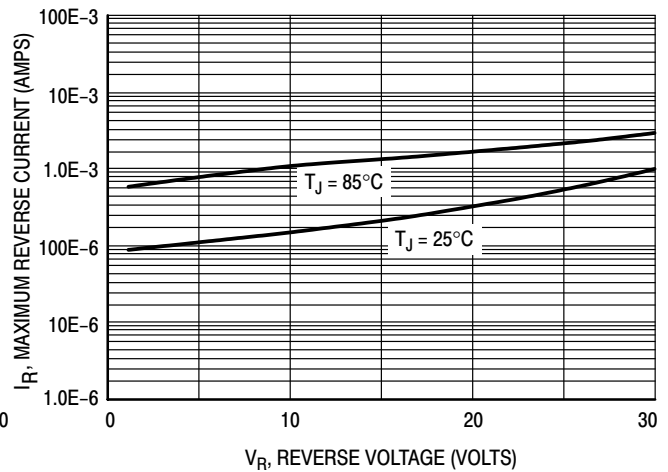
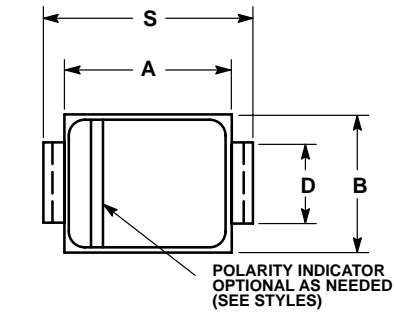


Figure 4. Maximum Reverse Current

# MBRA130LT3

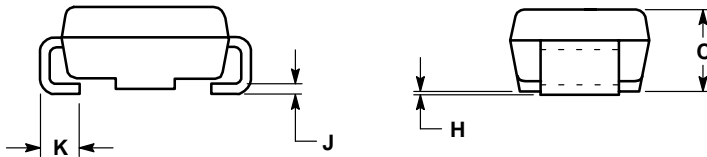
## PACKAGE DIMENSIONS

**SMA**  
CASE 403D-02  
ISSUE B

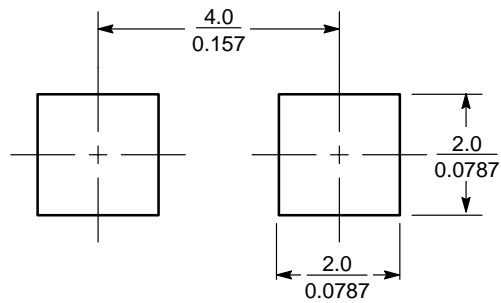


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.160	0.180	4.06	4.57
B	0.090	0.115	2.29	2.92
C	0.075	0.095	1.91	2.41
D	0.050	0.064	1.27	1.63
H	0.002	0.006	0.05	0.15
J	0.006	0.016	0.15	0.41
K	0.030	0.060	0.76	1.52
S	0.190	0.220	4.83	5.59



### SOLDERING FOOTPRINT\*



SCALE 8:1  $\left(\frac{\text{mm}}{\text{inches}}\right)$

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.